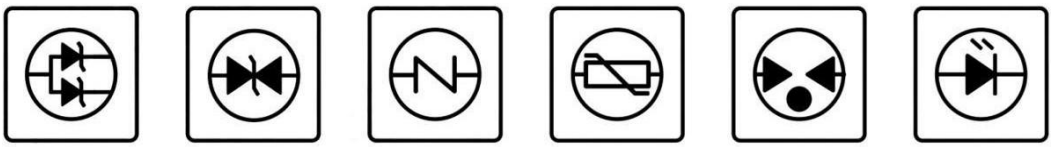
MSKSEMI 美森科
SEMICONDUCTOR



GBP6005-MS THRU GBP610-MS

Product specification

GBP6005-MS THRU GBP610-MS

REVERSE VOLTAGE - 50 to 1000 Volts
FORWARD CURRENT - 6.0 Amperes

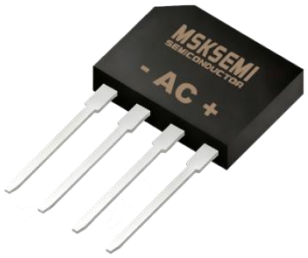
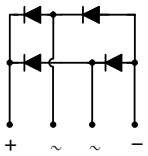
FEATURES

- Rating to 1000V PRV
- Ideal for printed circuit board
- Reliable low cost construction utilizing molded plastic technique
- The plastic material has UL flammability classification
- 94V#0

MECHANICAL DATA

- Polarity : As marked on body
- Weight : 0.05 ounces, 1.52 grams
- Mounting position : Any

REFERENCE NEWS

GBP



Marking

GBP6005-MS	GBP601-MS	GBP602-MS	GBP604-MS
			
GBP606-MS	**GBP608-MS**	**GBP610-MS**	
			

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25℃ ambient temperature unless otherwise specified.

CHARACTERISTICS	SYMBOL	GBP 6005-MS	GBP 601-MS	GBP 602-MS	GBP 604-MS	GBP 606-MS	GBP 608-MS	GBP 610-MS	UNIT
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified (With heatsink) Current @TC= 105 °C (Without heatsink)	$I_{(AV)}$	6.0 3.0							A
Peak Forward Surge Current 8.3ms single half sine-wave	I_{FSM}	150							A
Maximum Forward Voltage at 4.0A DC	V_F	1.1							V
Maximum DC Reverse Current at rated @Tj=25 °C Blocking Voltage @Tj= 125°C	I_R	5.0 500							uA
I^2t Rating for fusing (3ms≤t ≤8 .3ms)	I^2t	93							A^2S
Typical Junction Capacitance per element (Note 1)	C_J	46							pF
Typical thermal resistance(Unit mounted on 75mmx75mmx1 .6mm Copper plate heatsink.)	$R_{\Theta JC}$	3.0							°C/W
Typical thermal resistance (without heatsink)	$R_{\Theta JC}$	8.0							°C/W
Operation and Storage Temperature Range	T_J, T_{STG}	-55 to 150							°C

Note : (1) Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

RATINGAND CHARACTERISTIC CURVES (GBP6005-MS THRU GBP610-MS)

Fig.1 Average Rectified Output Current Derating Curve

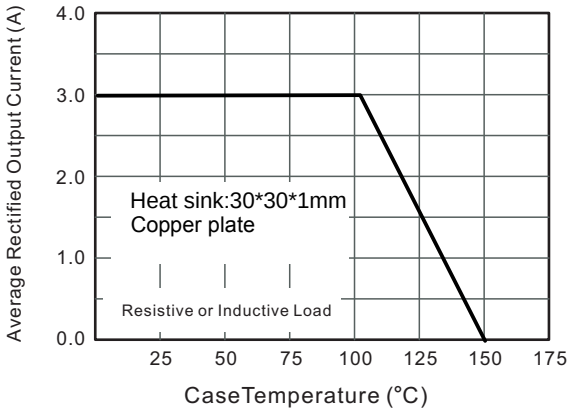


Fig.2 Typical Reverse Characteristics

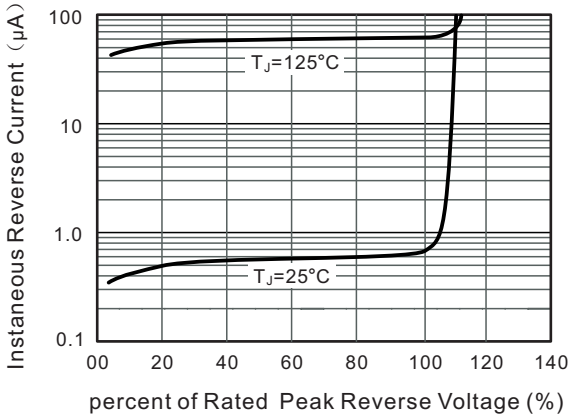


Fig.3 Typical Instaneous Forward Characteristics

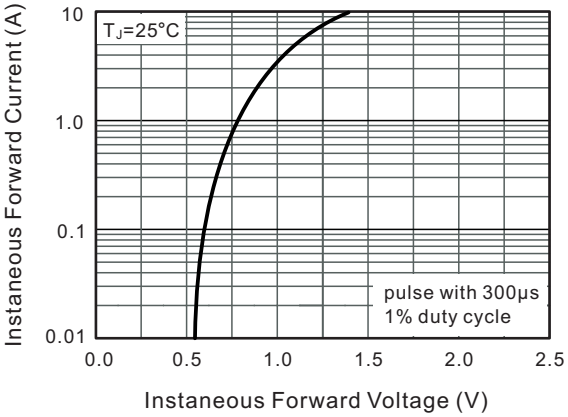
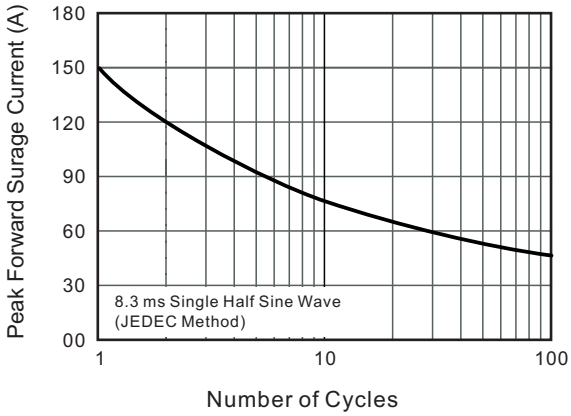
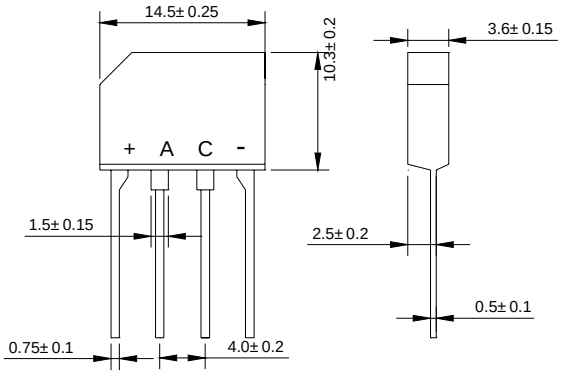


Fig.4 Maximum Non-Repetitive Peak Forward Surage Current



PACKAGE MECHANICAL DATA

GBP



Dimensions in millimeters

REELSPECIFICATION

P/N	PKG	QTY
GBP6005-MS THRU GBP610-MS	GBP	500

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